



**/ Descriptions**

Silicon PNP transistor in a SOT-23 Plastic Package.

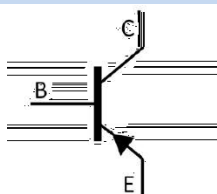
**/ Features**

Complementary pair with L8050M.

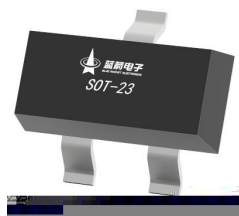
**/ Applications**

Power amplifier applications.

**/ Equivalent Circuit**



**/ Pinning**



PIN1 Base      PIN 2 Emitter      PIN 3 Collector

**/  $h_{FE}$  Classifications & Marking**

$h_{FE}$

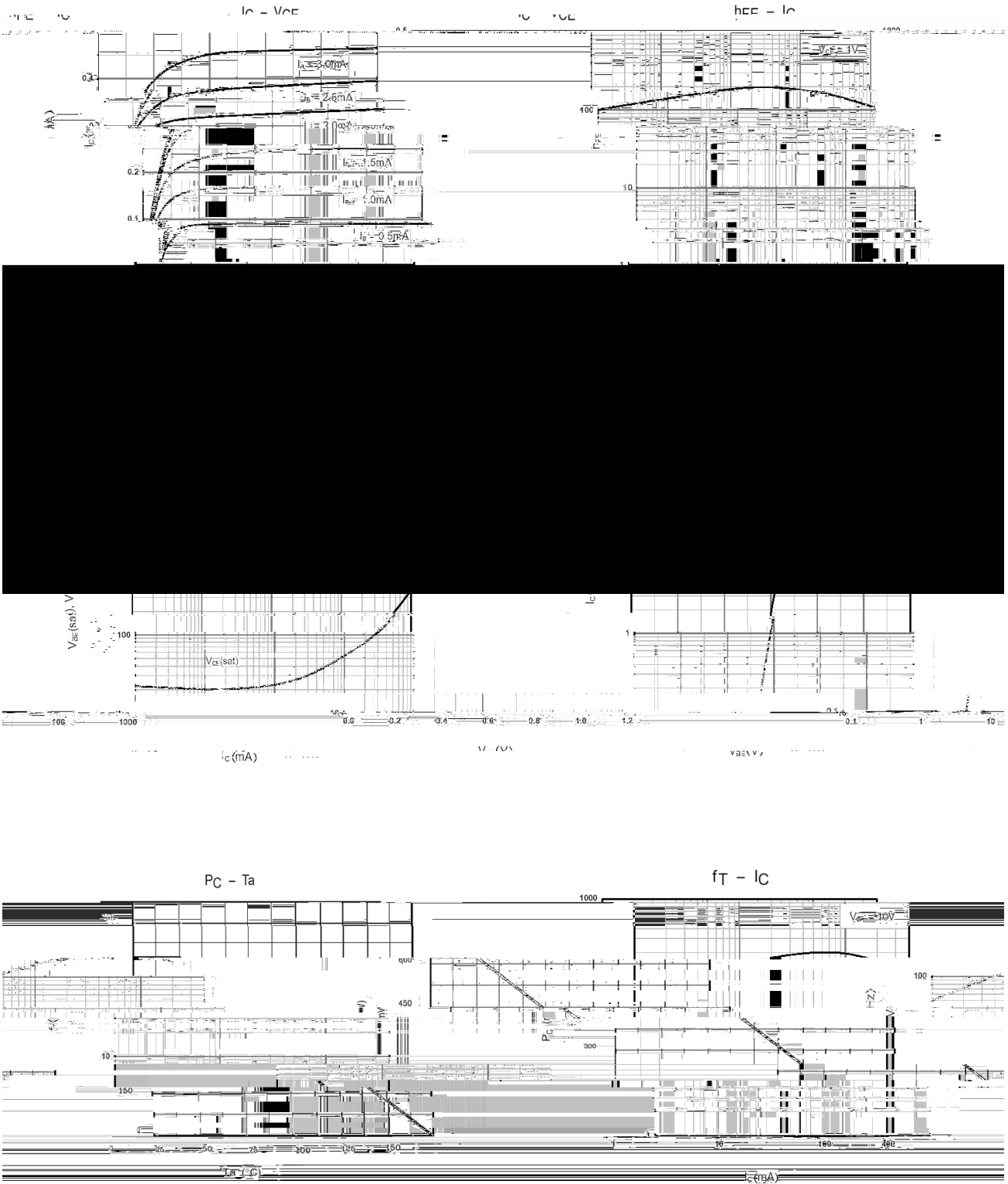
**/ Absolute Maximum Ratings(Ta=25 )**

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	-30	V
Collector to Emitter Voltage	$V_{CEO}$	-20	V
Emitter to Base Voltage	$V_{EBO}$	-6.0	V
Collector Current - Continuous	$I_C$	-1.5	A
Base Current - Continuous	$I_B$	-0.5	A
Collector Power Dissipation	$P_C$	300	mW
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

**/ Electrical Characteristics(Ta=25 )**

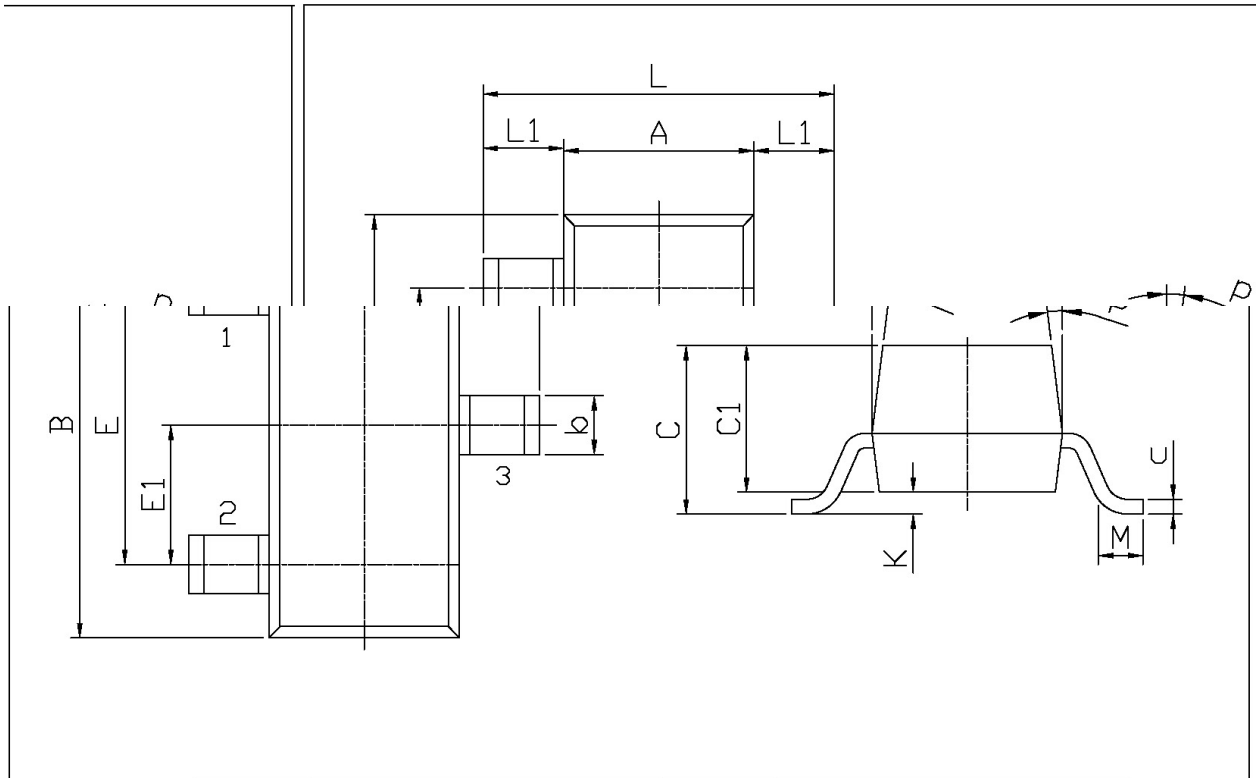
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=-0.1mA$ $I_E=0$	-30			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=-2.0mA$ $I_B=0$	-20			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E=-0.1mA$ $I_C=0$	-6.0			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=-30V$ $I_E=0$			-0.1	μA
Emitter Cut-Off Current	$I_{EBO}$	$V_{EB}=-6.0V$ $I_C=0$			-0.1	μA
DC Current Gain	$h_{FE(1)}$	$V_{CE}=-1.0V$ $I_C=-100mA$	85		300	
	$h_{FE(2)}$	$V_{CE}=-1.0V$ $I_C=-800mA$	40			
	$h_{FE(3)}$	$V_{CE}=-1.0V$ $I_C=-5.0mA$	45			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-800mA$ $I_B=-80mA$		-0.28	-0.5	V
Base to Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=-800mA$ $I_B=-80mA$		-0.98	-1.2	V
Base to Emitter Saturation Voltage	$V_{BE}$	$V_{CE}=-1.0V$ $I_C=-10mA$		-0.66	-1.0	V
Transition Frequency	$f_T$	$V_{CE}=-10V$ $I_C=-50mA$	100	200		MHz
Collector Output Capacitance	$C_{ob}$	$V_{CB}=-10V$ $f=1.0MHz$ $I_E=0$		15		pF

/ Electrical Characteristic Curve



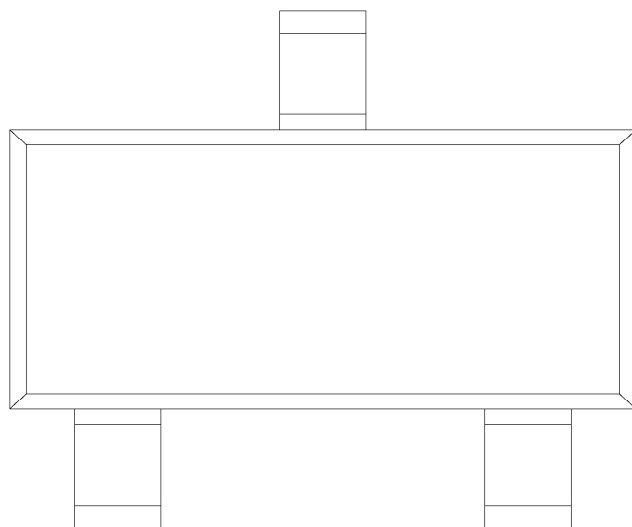
**/ Package Dimensions**

UNIT: mm



Symbol	Min.	Max.	Symbol	Min.
L	2.2	2.7	C	1.1
L1	0.45	0.65	C1	0.90
	1.15	1.50	e	0.15
B	2.70	3.20		
E	1.70	2.10		
E1	0.85	1.05		
b	0.35	0.55		

**/ Marking Instructions**



说明：

H： 为公司代码

Y2： 为型号代码

B： 为  $h_{FE}$  分档代码

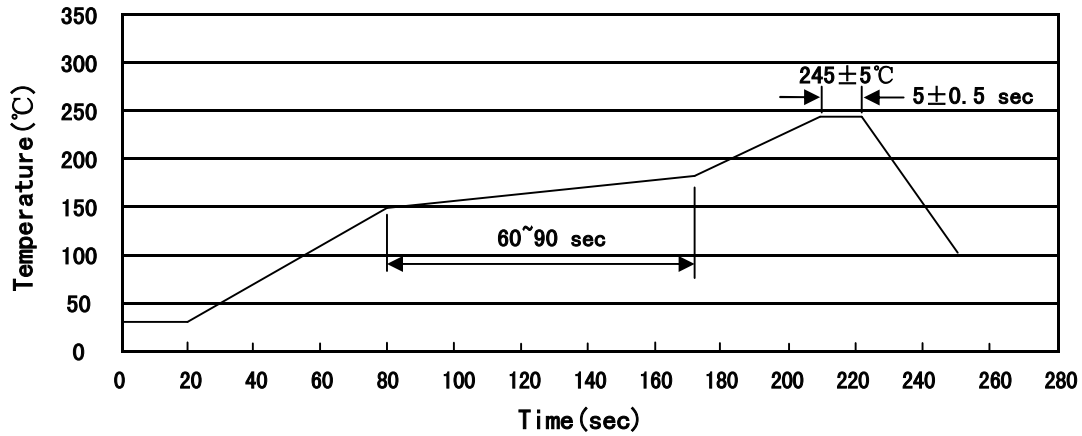
Note:

H: Company Code

Y2: Product Type Code

B:  $h_{FE}$

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
						盒	箱	
						"		

/ Notices